

REMARKS

Claims 1-11 have been canceled. Claims 12-22 are pending.

Independent claim 12 recites a semiconductor device in which a first semiconductor element is sealed by a sealing resin, wherein the sealing resin has a cavity portion in which a second semiconductor element is stored.

As illustrated in the example of FIGS. 1A-1B, a first element 15A is sealed by sealing resin 16 which has a cavity 18. A second element 15B is stored in the cavity.

Such an arrangement may facilitate replacing the second element in the event that it fails or in the event that an element with a different function is to be used instead. Since the second element is stored in a cavity in the sealing resin, it is easier to remove that element should that become necessary or desirable.

Applicant thanks the Examiner for recognizing that claims 6, 7, 10 and 11 include allowable subject matter. Those claims have been rewritten, respectively, with clarifying amendments, as claims 17, 18, 21 and 22.

The other claims were rejected over the cited references as follows:

(1) Claims 1-5 and 8-9 were rejected as anticipated by U.S. Patent No. 6,774,469 (Utsumi).

(2) Claims 1, 3 and 9 were rejected as anticipated by U.S. Patent No. 4,663,833 (Tanaka et al.).

As discussed below, applicant respectfully submits that the pending claims are patentable over the cited references.

The Utsumi patent discloses a semiconductor memory card that includes a control IC 10 and flash memory 11. (FIGS. 3 and 4) The housing of the memory card is formed of a resin, which may be partially transparent. However, as shown, for example, in FIG. 4, both the control

IC 10 and the memory 11 are sealed within the same resin housing. Contrary to the statement in the Office action, the Utsumi patent does not disclose a circuit element that is provided in a cavity *in the sealing resin*. The feature identified by reference numeral 4 in FIGS. 3 and 4 of the Utsumi patent refers to a label adhesion face *on the card housing* (see, e.g., col. 4, line 48-51; col. 6, lines 120-23). The difference between FIGS. 3 and 4 of the Utsumi patent is that in FIG. 3, the entire card housing is transparent, whereas in FIG. 4, only the label adhesion face is transparent. In any event, the housings disclosed in the Utsumi patent do not include a sealing resin with a cavity portion in which a second semiconductor element is stored.

For similar reasons, independent claims 16 and 20 also are patentable distinguishable from the Utsumi patent.

The Tanaka et al. patent discloses a plastic IC package with a light receiving window. The package may be formed of a resin (col. 3, line 36). An IC chip 125 is bonded to the lead frame in a mounting area 102. Even if the mounting area were considered to correspond to a cavity portion in the sealing resin, the Tanaka et al. patent discloses only a single IC chip in the package. There is no suggestion of including another semiconductor element as recited in the pending claims. Instead, the IC chip 125 is electrically connected to leads 104 extending to the exterior of the package.

In view of the foregoing amendments and remarks, applicant respectfully requests withdrawal of the rejections.

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this

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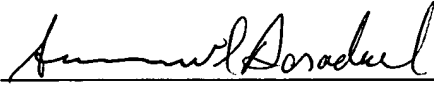
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paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to its amendment.

Please apply any other charges or credits to deposit account 06-1050.

Respectfully submitted,

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